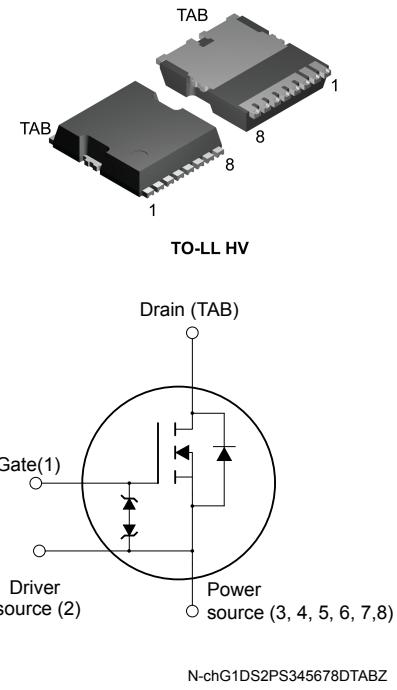


## N-channel 600 V, 105 mΩ typ., 25 A, MDmesh™ M6 Power MOSFET in a TO-LL HV package

### Features



| Order code | V <sub>DS</sub> | R <sub>DS(on)</sub> max. | I <sub>D</sub> |
|------------|-----------------|--------------------------|----------------|
| STO33N60M6 | 600 V           | 125 mΩ                   | 25 A           |

- Reduced switching losses
- Lower R<sub>DS(on)</sub> per area vs previous generation
- Low gate input resistance
- 100% avalanche tested
- Zener-protected
- High creepage package
- Excellent switching performance thanks to the extra driving source pin

### Applications

- Switching applications
- LLC converters
- Boost PFC converters

### Description

The new MDmesh™ M6 technology incorporates the most recent advancements to the well-known and consolidated MDmesh family of SJ MOSFETs. STMicroelectronics builds on the previous generation of MDmesh devices through its new M6 technology, which combines excellent R<sub>DS(on)</sub> per area improvement with one of the most effective switching behaviors available, as well as a user-friendly experience for maximum end-application efficiency.

| Product status link        |               |
|----------------------------|---------------|
| <a href="#">STO33N60M6</a> |               |
| Product summary            |               |
|                            |               |
| Order code                 | STO33N60M6    |
| Marking                    | 33N60M6       |
| Package                    | TO-LL HV      |
| Packing                    | Tape and reel |

## 1 Electrical ratings

**Table 1. Absolute maximum ratings**

| Symbol        | Parameter  | Value      | Unit       |
|---------------|--|------------|------------|
| $V_{GS}$      | Gate-source voltage                                    | $\pm 25$   | V          |
| $I_D$         | Drain current (continuous) at $T_{case} = 25^\circ C$  | 25         | A          |
|               | Drain current (continuous) at $T_{case} = 100^\circ C$ | 15.8       |            |
| $I_D^{(1)}$   | Drain current (pulsed)                                 | 78         | A          |
| $P_{TOT}$     | Total dissipation at $T_{case} = 25^\circ C$           | 230        | W          |
| $dv/dt^{(2)}$ | Peak diode recovery voltage slope                      | 15         | V/ns       |
|               | MOSFET dv/dt ruggedness                                | 50         |            |
| $T_{stg}$     | Storage temperature range                              | -55 to 150 | $^\circ C$ |
| $T_j$         | Operating junction temperature range                   |            |            |

1. Pulse width limited by safe operating area.
2.  $I_{SD} \leq 25 A$ ,  $di/dt \leq 400 A/\mu s$ ,  $V_{DS(peak)} < V_{(BR)DSS}$ ,  $V_{DD} = 400 V$
3.  $V_{DS} \leq 480 V$

**Table 2. Thermal data**

| Symbol         | Parameter                        | Value | Unit         |
|----------------|----------------------------------|-------|--------------|
| $R_{thj-case}$ | Thermal resistance junction-case | 0.54  | $^\circ C/W$ |
| $R_{thj-pcb}$  | Thermal resistance junction-pcb  | 46    | $^\circ C/W$ |

**Table 3. Avalanche characteristics**

| Symbol   | Parameter  | Value | Unit |
|----------|--|-------|------|
| $I_{AR}$ | Avalanche current, repetitive or non-repetitive<br>(pulse width limited by $T_{Jmax}$ )            | 4     | A    |
| $E_{AS}$ | Single pulse avalanche energy<br>(starting $T_j = 25^\circ C$ , $I_D = I_{AR}$ , $V_{DD} = 50 V$ ) | 500   | mJ   |

## 2 Electrical characteristics

( $T_{case} = 25^\circ\text{C}$  unless otherwise specified)

**Table 4. On/off states**

| Symbol              | Parameter                         | Test conditions  | Min. | Typ. | Max.    | Unit             |
|---------------------|-----------------------------------|--|------|------|---------|------------------|
| $V_{(BR)DSS}$       | Drain-source breakdown voltage    | $V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$   | 600  |      |         | V                |
| $I_{DSS}$           | Zero gate voltage drain current   | $V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}$                                     |      |      | 1       | $\mu\text{A}$    |
|                     |                                   | $V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_{case} = 125^\circ\text{C}^{(1)}$ |      |      | 100     |                  |
| $I_{GSS}$           | Gate-body leakage current         | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$                                  |      |      | $\pm 5$ | $\mu\text{A}$    |
| $V_{GS(\text{th})}$ | Gate threshold voltage            | $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$   | 3.25 | 4    | 4.75    | V                |
| $R_{DSS(on)}$       | Static drain-source on-resistance | $V_{GS} = 10 \text{ V}, I_D = 12.5 \text{ A}$                                      |      | 105  | 125     | $\text{m}\Omega$ |

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

| Symbol                      | Parameter                     | Test conditions  | Min. | Typ. | Max. | Unit        |
|-----------------------------|-------------------------------|--|------|------|------|-------------|
| $C_{iss}$                   | Input capacitance             | $V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$  | -    | 1515 | -    | $\text{pF}$ |
| $C_{oss}$                   | Output capacitance            |  | -    | 128  | -    |             |
| $C_{rss}$                   | Reverse transfer capacitance  |  | -    | 4.2  | -    |             |
| $C_{oss \text{ eq.}}^{(1)}$ | Equivalent output capacitance | $V_{DS} = 0 \text{ to } 480 \text{ V}, V_{GS} = 0 \text{ V}$   | -    | 269  | -    | pF          |
| $R_G$                       | Intrinsic gate resistance     | $f = 1 \text{ MHz}, I_D = 0 \text{ A}$   | -    | 1.5  | -    | $\Omega$    |
| $Q_g$                       | Total gate charge             | $V_{DD} = 480 \text{ V}, I_D = 25 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$<br>(see Figure 14. Gate charge test circuit) | -    | 33.4 | -    | $\text{nC}$ |
| $Q_{gs}$                    | Gate-source charge            |  | -    | 7.2  | -    |             |
| $Q_{gd}$                    | Gate-drain charge             |  | -    | 16.3 | -    |             |

1.  $C_{oss \text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

| Symbol       | Parameter           | Test conditions  | Min. | Typ. | Max. | Unit |
|--------------|---------------------|--|------|------|------|------|
| $t_{d(on)}$  | Turn-on delay time  | $V_{DD} = 300 \text{ V}, I_D = 12.5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$<br>(see Figure 13. Switching times test circuit for resistive load and Figure 18. Switching time waveform) | -    | 19.5 | -    | ns   |
| $t_r$        | Rise time           |  | -    | 33   | -    |      |
| $t_{d(off)}$ | Turn-off delay time |  | -    | 38.5 | -    |      |
| $t_f$        | Fall time           |  | -    | 7.5  | -    |      |

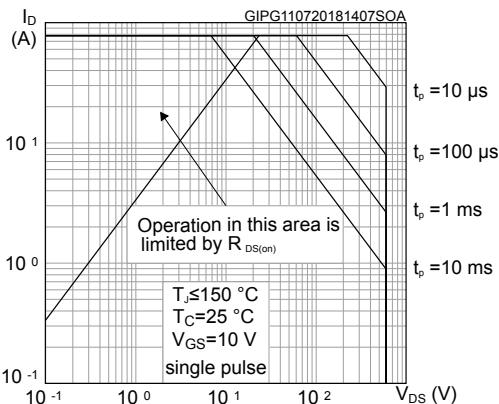
Table 7. Source-drain diode

| Symbol          | Parameter                     | Test conditions   | Min. | Typ. | Max. | Unit          |
|-----------------|-------------------------------|---|------|------|------|---------------|
| $I_{SD}$        | Source-drain current          |   | -    |      | 25   | A             |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) |   | -    |      | 78   | A             |
| $V_{SD}^{(2)}$  | Forward on voltage            | $I_{SD} = 25 \text{ A}, V_{GS} = 0 \text{ V}$   | -    |      | 1.6  | V             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 25 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$<br>$V_{DD} = 60 \text{ V}$                          | -    | 265  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       | (see Figure 15. Test circuit for<br>inductive load switching and diode<br>recovery times)                       | -    | 3.07 |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |   | -    | 23.2 |      | A             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 25 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$<br>$V_{DD} = 60 \text{ V}, T_j = 150^\circ\text{C}$ | -    | 374  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       | (see Figure 15. Test circuit for<br>inductive load switching and diode<br>recovery times)                       | -    | 5.78 |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |   | -    | 30.9 |      | A             |

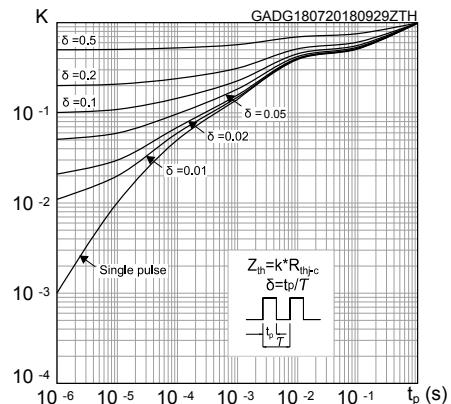
1. Pulse width is limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

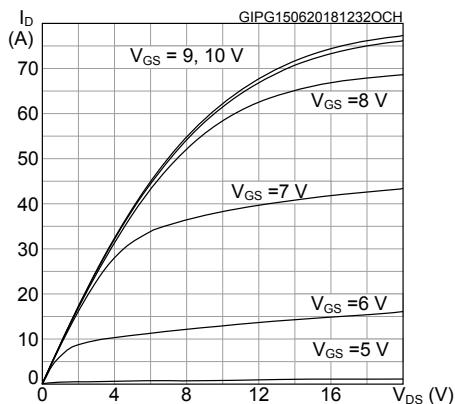
**Figure 1. Safe operating area**



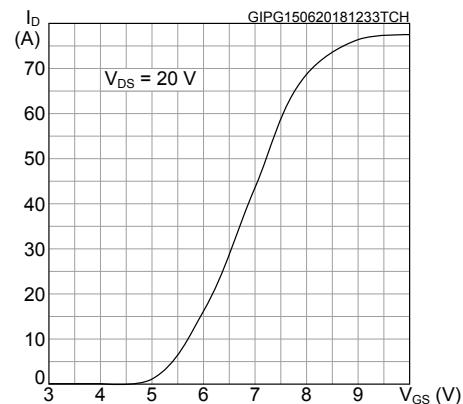
**Figure 2. Thermal impedance**



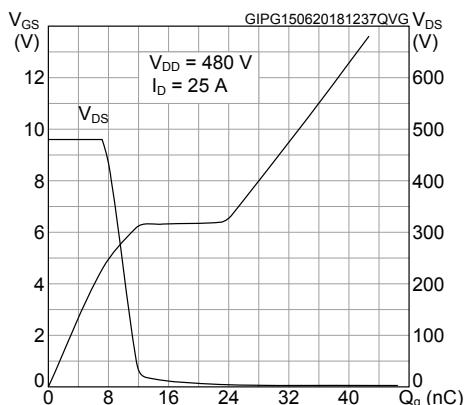
**Figure 3. Output characteristics**



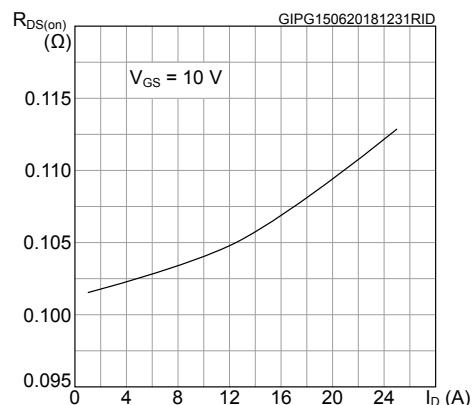
**Figure 4. Transfer characteristics**

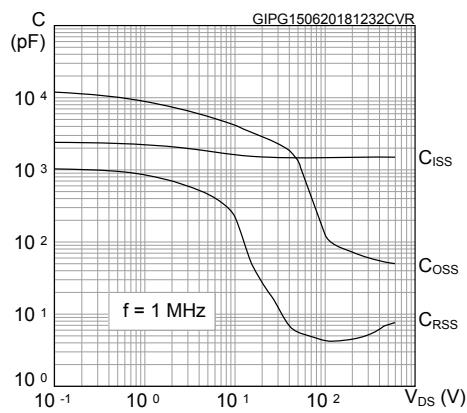
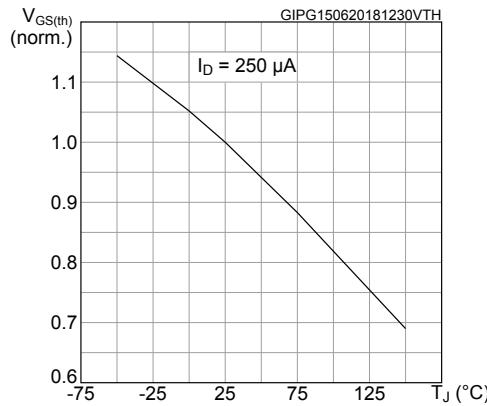
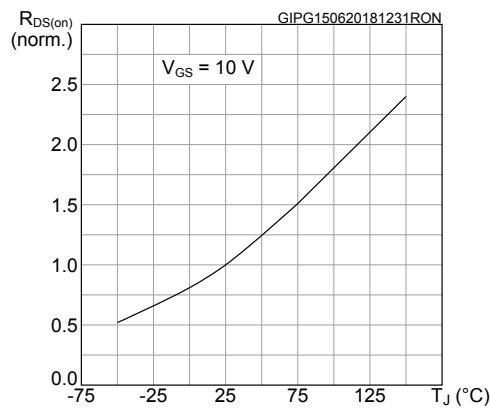
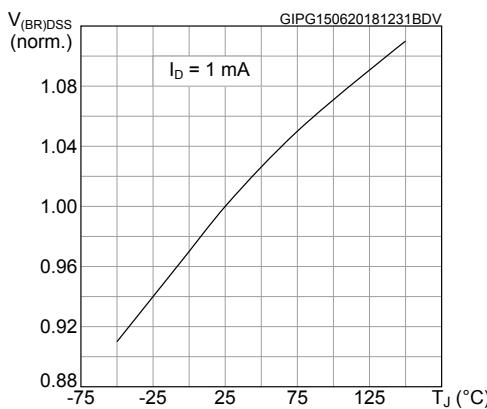
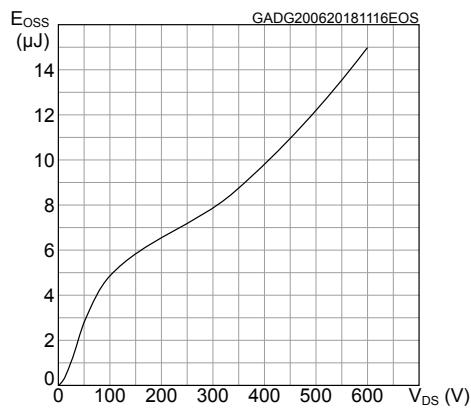
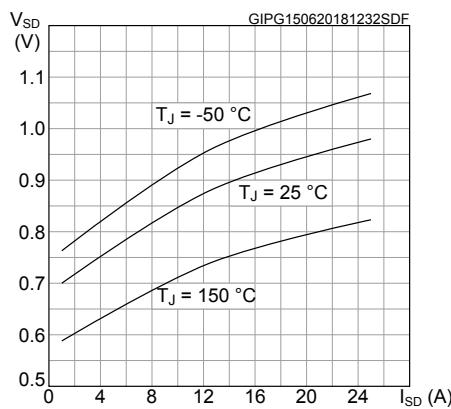


**Figure 5. Gate charge vs gate-source voltage**



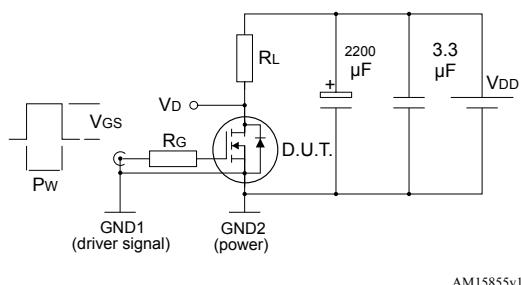
**Figure 6. Static drain-source on-resistance**



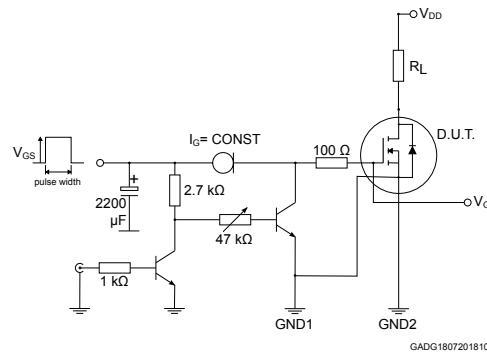
**Figure 7. Capacitance variations**

**Figure 8. Normalized gate threshold voltage vs temperature**

**Figure 9. Normalized on-resistance vs temperature**

**Figure 10. Normalized V\_(BR)DSS vs temperature**

**Figure 11. Output capacitance stored energy**

**Figure 12. Source-drain diode forward characteristics**


### 3 Test circuits

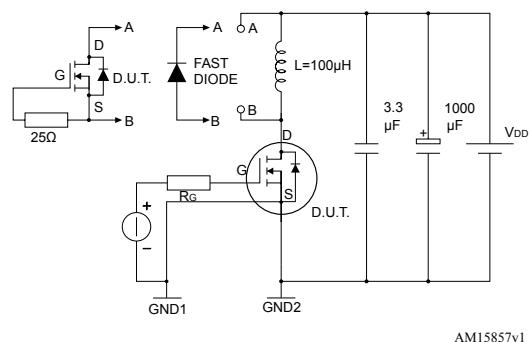
**Figure 13.** Switching times test circuit for resistive load



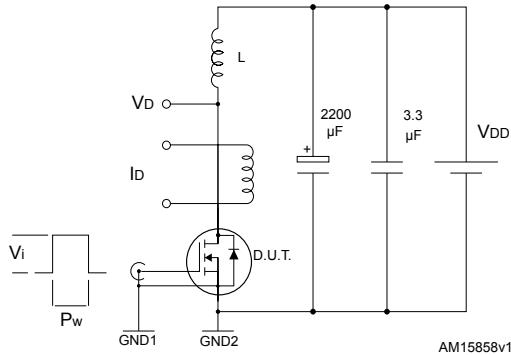
**Figure 14.** Gate charge test circuit



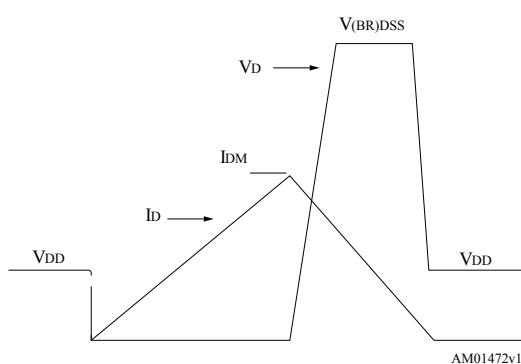
**Figure 15.** Test circuit for inductive load switching and diode recovery times



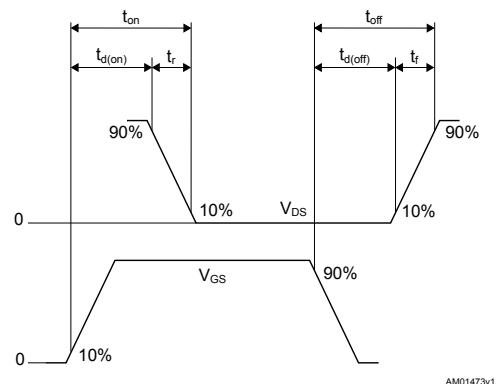
**Figure 16.** Unclamped inductive load test circuit



**Figure 17.** Unclamped inductive waveform



**Figure 18.** Switching time waveform

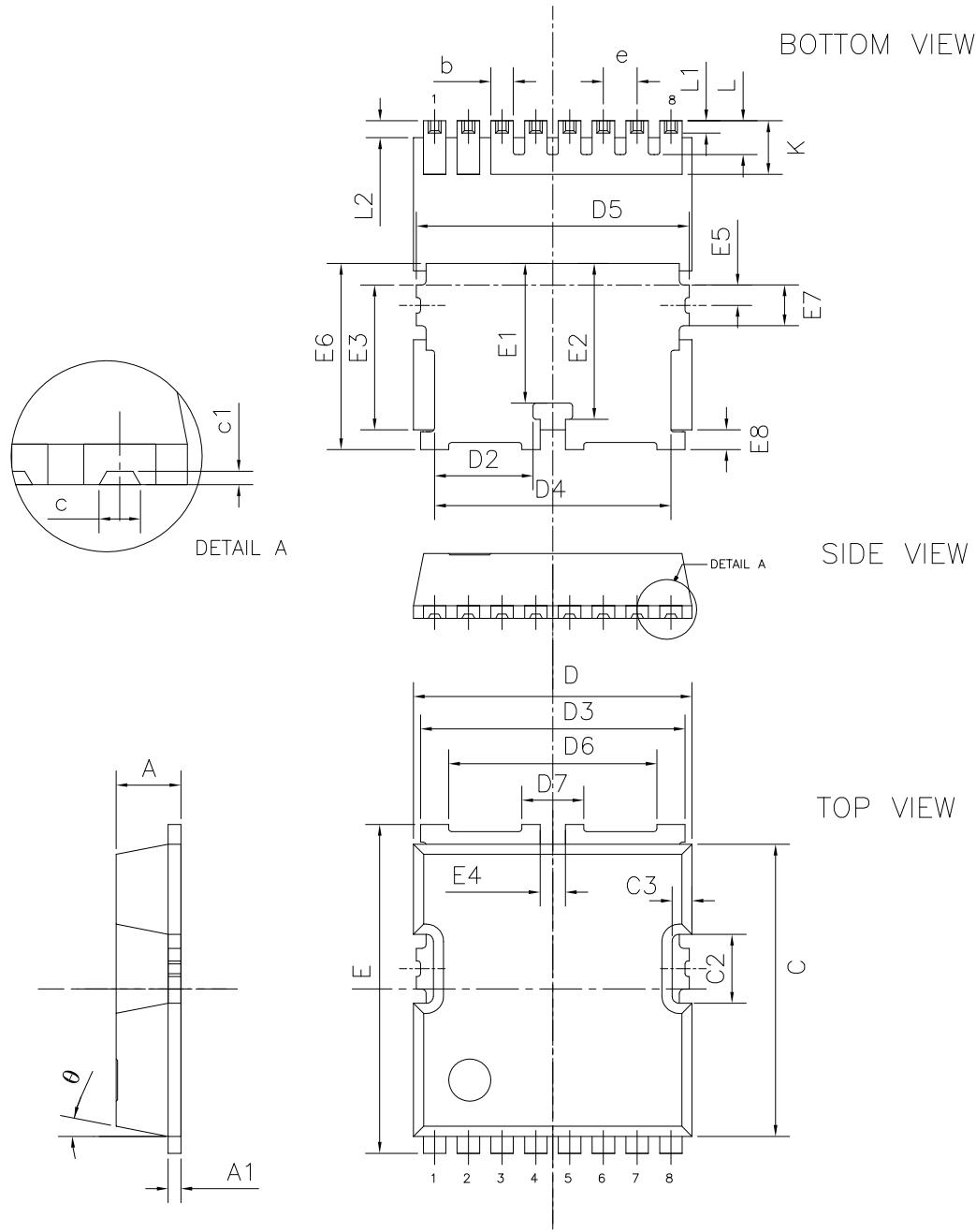


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 TO-LL HV package information

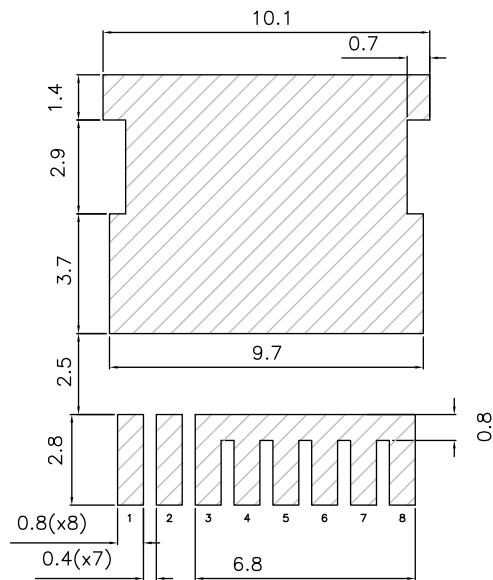
Figure 19. TO-LL HV package outline



**Table 8.** TO-LL HV package mechanical data

| Dim. | mm    |       |       |
|------|-------|-------|-------|
|      | Min.  | Typ.  | Max.  |
| A    | 2.20  | 2.30  | 2.40  |
| A1   | 0.40  | 0.48  | 0.60  |
| b    |       | 0.80  | 0.93  |
| c    |       | 0.46  |       |
| c1   |       | 0.15  |       |
| C    | 10.28 | 10.38 | 10.48 |
| C2   | 2.35  | 2.45  | 2.55  |
| C3   |       | 0.71  |       |
| D    | 9.80  | 9.90  | 10.00 |
| D2   | 3.30  | 3.50  | 3.70  |
| D3   | 9.30  | 9.40  | 9.50  |
| D4   | 8.20  | 8.40  | 8.60  |
| D5   | 9.50  | 9.70  | 9.90  |
| D6   |       | 7.40  |       |
| D7   |       | 2.20  |       |
| e    |       | 1.20  |       |
| E    | 11.48 | 11.68 | 11.88 |
| E1   |       | 4.96  |       |
| E2   |       | 5.54  |       |
| E3   |       | 5.14  |       |
| E4   |       | 0.90  |       |
| E5   |       | 0.72  |       |
| E6   | 6.41  | 6.61  | 6.81  |
| E7   | 0.50  | 0.70  | 0.90  |
| K    | 1.70  | 1.90  | 2.10  |
| L    | 1.05  | 1.20  | 1.35  |
| L1   | 0.25  | 0.35  | 0.45  |
| L2   | 0.40  | 0.60  | 0.80  |
| θ    |       | 11°   |       |

**Figure 20.** TO-LL HV recommended footprint (dimensions are in mm)



DM00276569\_1

## Revision history

**Table 9. Document revision history**

| Date        | Version | Changes          |
|-------------|---------|------------------|
| 11-Jul-2018 | 1       | Initial release. |

## Contents

|            |                                     |           |
|------------|-------------------------------------|-----------|
| <b>1</b>   | <b>Electrical ratings</b>           | <b>2</b>  |
| <b>2</b>   | <b>Electrical characteristics</b>   | <b>3</b>  |
| <b>2.1</b> | Electrical characteristics (curves) | 5         |
| <b>3</b>   | <b>Test circuits</b>                | <b>7</b>  |
| <b>4</b>   | <b>Package information</b>          | <b>8</b>  |
| <b>4.1</b> | TO-LL HV package information        | 8         |
|            | <b>Revision history</b>             | <b>11</b> |

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**Наши контакты:**

**Телефон:** +7 812 627 14 35

**Электронная почта:** [sales@st-electron.ru](mailto:sales@st-electron.ru)

**Адрес:** 198099, Санкт-Петербург,  
Промышленная ул, дом № 19, литер Н,  
помещение 100-Н Офис 331